Bryan, TX 77801

979-985-8599 SOURABH S. SHENOY

EDUCATION

TEXAS A&M UNIVERSITY, COLLEGE STATION (TAMU)

Fall '16 - Summer '18 (Expected) Master of Science (MS), Computer Science

VISVESVARAYA TECHNOLOGICAL UNIVERSITY (VTU), INDIA

2012 - 2016 Bachelor of Engineering (BE), Computer Science

EXPERIENCE

MICROSOFT MENTORSHIP, MTC

AUGUST 2014 - MARCH 2015

sourabhsshenoy@tamu.edu

CGPA:

CGPA:

Implemented various Buffer page replacement policies in PostgreSQL Database as proof of concept

INTERN, INFOSYS MANGALORE (Catch Them Young 2009)

SUMMER 2010

4.0/4.0

9.24/10

Developed a tool that allowed around 5000 Infosys Employees to book/cancel shuttles

Technologies Used: HTML5, CSS, JavaScript, JQuery, MS Access, SQL, JSP

SKILLS

Programming Languages : Python, C, C++, CUDA

Web Technologies : HTML5, CSS3, JavaScript, WordPress, Bootstrap Framework,

Database : MySQL, PostgreSQL **Platforms** : Windows, Linux

Others : AppleScript, Shell Script, GitHub, NVidia Visual Profiler

GitHub Link : https://github.com/sourabhshenoy

MAJOR PROJECTS

SOURCE CODE CLASSIFIER USING NLPTOOLS

FALL 2016

Developing an extension to PopClip, a popular Mac app, that can automatically identify the highlighted code snippet (In 13 languages) and execute it online or locally. Languages Used: PHP, AppleScript

UTILITIES FOR PORTING TCP EVALUATION SUITE TO NS3

FINAL YEAR PROJECT (2015)

- Developed modules to collect statistics from bottleneck links and plot graphs for the same
- Integrated Tmix and DelayBox modules into NS 3.24 and wrote Test suite and Example script
- Contributed to 2 Google Summer of Code (GSoC) projects. Language Used: C++

SWIFT - AN OPTIMIZED STRING MATCHING ALGORITHM FOR NVIDIA GPU

SUMMER 2015

- Work accepted for poster presentation at Student Research Symposium (SRS), co-located with IEEE Conference on HiPC, 2015. API Used: CUDA, C++, OpenMP, MPI
- Accepted for full oral presentation at International Symposium on Parallel and Distributed Computing (ISPDC), 2016, held in China.
- Won IEEE TCPP award for "Best Poster". Received scholarship from IEEE HiPC, National Science Foundation (NSF) and TEQUIP program of World Bank amounting to around \$2000